REMARKS

Claims 1-10 have been examined, with all of these claims rejected based on prior art. Claims 2-5 have been canceled, and claims 11-13 have been added. Thus, claims 1 and 6-13 are pending.

Applicant thanks the Examiner for conducting the telephonic interview held on November 9, 2004. The substance of this interview is reflected in the remarks below.

Claims 1-9 have been rejected under 35 U.S.C. § 102(e) as being anticipated by Lasch et al. (U.S. Patent No. 6,581,839), and claims 1 and 10 have been rejected under 35 U.S.C. § 102(e) as being anticipated by Kohama et al. (U.S. Patent No. 6,412,701).

During the interview the Examiner acknowledged that the original claims distinguish over Lasch because Lasch does not teach the claimed component. Thus, the Examiner agreed to withdraw the prior art rejection based on Lasch.

The present invention is directed to a chip module having a semiconductor chip 4 fixed on a main side of a planar substrate 1, at least one electrically conductive connection 3 fitted on the main side of the substrate and connected to a connecting contact of the semiconductor chip, and a display device, which takes up, emits, reflects or partially shields electromagnetic radiation in the range of visible wavelengths, provided on the main side of the substrate and connected to the at least one electrically conductive connection. The substrate is a film which is transmissive to the radiation to permit the radiation to be taken up, emitted, reflected or partially shielded, by the display device.

Kohama is directed to a flexible IC module having an IC chip 1 and a coil 2 embedded in a flexible substrate 3 comprising a fabric, and a method of producing this flexible IC module. See, for example, Fig. 8. The module may also have an image display device. See col. 3, line 48.

Kohama does not teach (or even suggest) a display device provided on a substrate film which is transmissive to radiation in the range of visible wavelengths, as required by the amended

claims. The claimed substrate film offers an easy means to integrate a display device and a semiconductor chip into a chip module, which can be arranged at a surface of a chip card body. Although the embodiment shown in Fig. 1 of Kohama requires a substrate material which is transmissive to the radiation that is transmitted or received by the antenna, there is no indication that the substrate material should be transmissive to radiation in the range of visible wavelengths, as required by the claimed invention. The claims are patentable over Kohama.

In view of the above amendment, applicant believes the pending application is in condition for allowance.

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Respectfully submitted,

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